

F

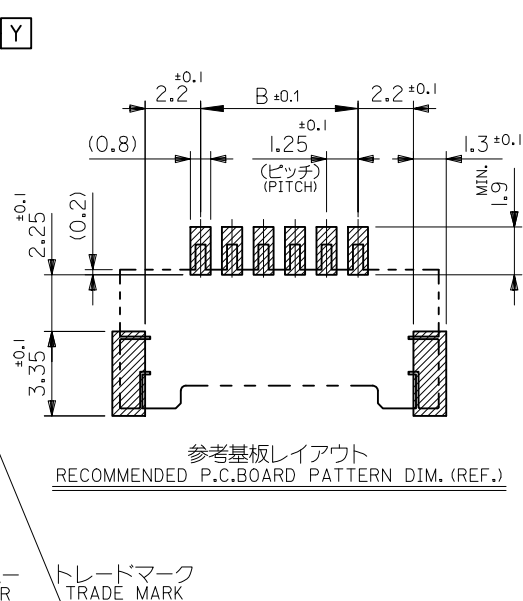
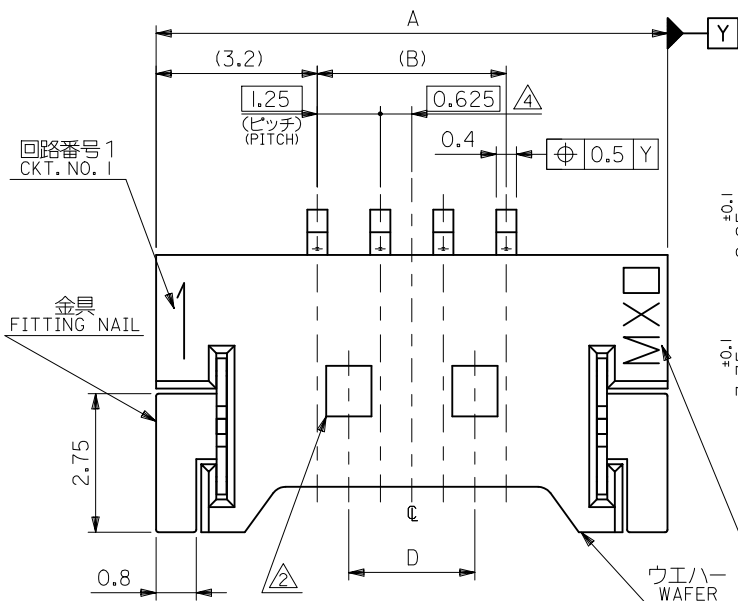
E

D

C

B

A



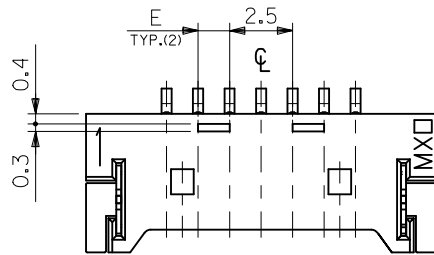
注記 NOTES

1. 嵌合相手: 51146 シリーズ
MATES WITH : 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、上方向に 0.05MAX.、下方向に 0.15MAX. とし、20 極以下の相互のバラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V] : UPPER DIRECTION 0.05MAX. : LOWER DIRECTION 0.15MAX. : OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハ WAFER : PPS, UL94V-0
ピン: リン青銅 PIN: PHOSPHOR BRONZE
コンタクト部: 金メッキ 0.2 マイクロメートル以上
CONTACT AREA: GOLD 0.2 MICROMETER MINIMUM
テール部: 錫メッキ 3.0 マイクロメートル以上
TAIL AREA: TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
金具: リン青銅 FITTING NAIL: PHOSPHOR BRONZE
錫メッキ 3.0 マイクロメートル以上
TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
6. 本製品は 53780-**-**10/-**-**18 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780-**-**10/-**-**18.
7. ELV 及び RoHS 適合品
ELV & RoHS COMPLIANT.

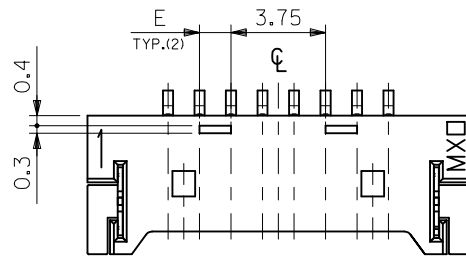
16.25	22.5	38.77	36.25	42.65	53780-3070	30
8.75	22.5	26.27	23.75	30.15	-2070	20
7.5	20	23.77	21.25	27.65	-1870	18
6.25	16.25	20.02	17.5	23.9	-1570	15
5	15	18.77	16.25	22.65	-1470	14
3.75	12.5	16.27	13.75	20.15	-1270	12
2.5	10	13.77	11.25	17.65	-1070	10
2.5	8.75	12.52	10	16.4	-0970	9
1.25	7.5	11.27	8.75	15.15	-0870	8
1.25	6.25	10.02	7.5	13.9	-0770	7
--	5	8.77	6.25	12.65	-0670	6
--	3.75	7.52	5	11.4	-0570	5
--	2.5	6.27	3.75	10.15	-0470	4
--	--	5.02	2.5	8.9	-0370	3
--	--	3.77	1.25	7.65	53780-0270	2
E	D	C	B	A	EMBOSSED PACKAGE	CKT.
					オーダー番号 ORDER No.	極数

CONNECTOR SERIES NO. 53780-**-**19

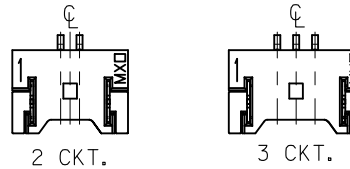
REVISED EC NO: J2010-1927 DRWN: KUROSE 2010/03/25 CHKD: KASAKAWA 2010/03/26 APPR: NUKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/15	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53780-003
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



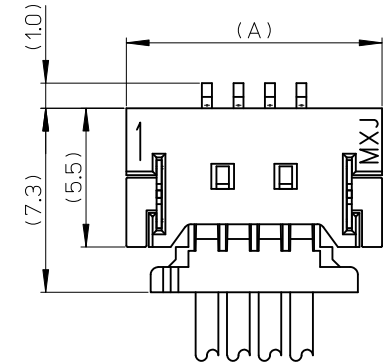
7~19極の奇数極に適用
 APPLY FOR ODD CIRCUITS OF 7~19



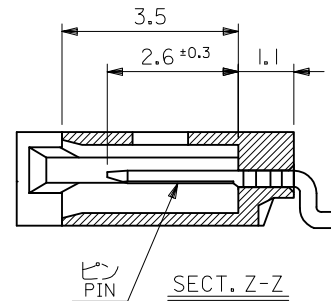
8~30 極の偶数極に適用
 APPLY FOR EVEN CIRCUITS OF 8~30



ロック形状図
 LOCK CONFIGURATION



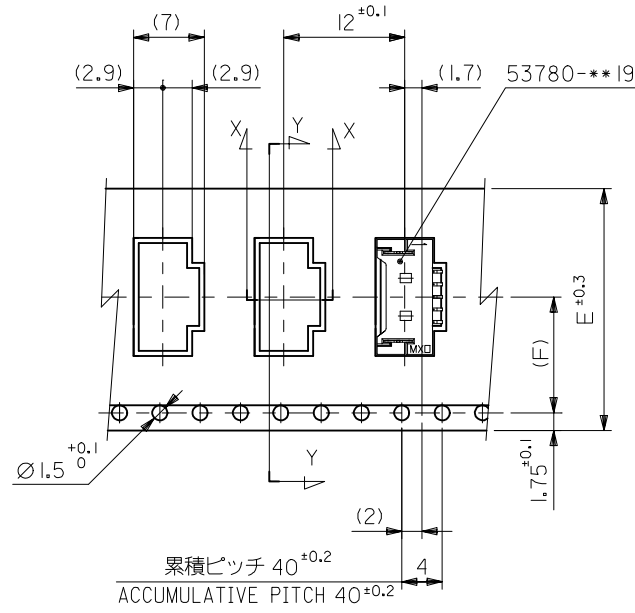
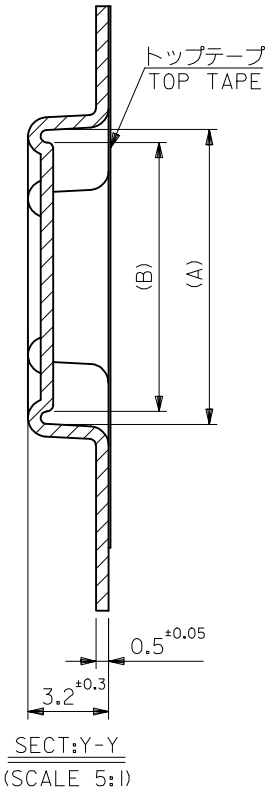
嵌合図 (SCALE 5:1)
 MATED CONNECTORS (SCALE 5:1)



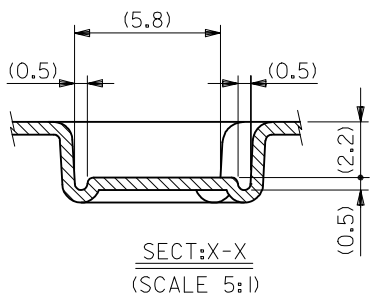
PIN SECT. Z-Z

CONNECTOR SERIES NO. 53780-**19

REVISED EC NO.: J2010-1927 DRWN:SKUROSE 2010/03/25 CHKD:KASAKAWA 2010/03/26 APPR:NUKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/15	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53780-003
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

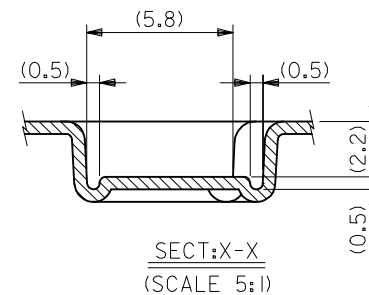
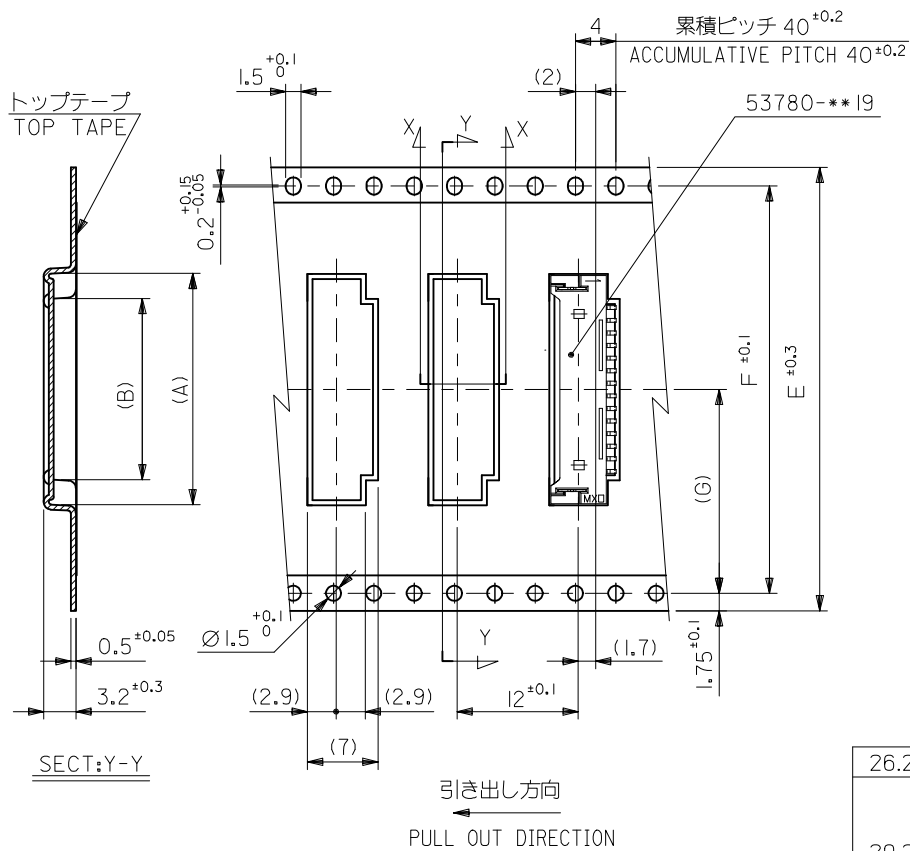


引き出し方向
PULL OUT DIRECTION



11.5	24	29.4	25.4	11.75	16.7	53780-0970	9
				10.5	15.45	53780-0870	8
				9.25	14.2	53780-0770	7
				8	12.95	53780-0670	6
				6.75	11.7	53780-0570	5
7.5	16	21.4	17.4	4.25	9.2	53780-0370	3
				3	7.95	53780-0270	2
(F)	E	D	C	(B)	(A)	MATERIAL NO.	種数 CKT.
						MODEL NO.	53780-***70

REVISED EC NO: J2010-0021 DRWN: TAKASAKI CHKD: HAYASHI APPR: NUKITA	DESCRIPTION 2009/07/07 2009/07/08 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B WAFER ASSY EMBOSSED TAPE PACKAGE					
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/15	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53780-004		SHEET NO. 2 OF 3	
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



26.2	52.4	56	61.4	57.4	38	42.95	53780-3070	30
20.2	40.4	44	49.4	45.4	25.5	30.45	53780-2070	20
					25.5	27.95	53780-1870	18
					19.25	24.2	53780-1570	15
					18	22.95	53780-1470	14
14.2	28.4	32	37.4	33.4	15.5	20.45	53780-1270	12
					13	17.95	53780-1070	10
(G)	F	E キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CKT.

引き出し方向
PULL OUT DIRECTION

REVISED EC NO: J2010-0021 DRWN:MTAKASAKI 2009/07/07 CHKD:MHAYASHI 2009/07/08 APPR:NUKITA 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		MODEL NO. 53780-***70	
	10 UNDER ±0.2		DRAWN BY T.UENO		DATE '04/04/15		TITLE 1.25 W/B WAFER ASSY EMBOSSED TAPE PACKAGE	
	10 OVER 30 UNDER ±0.25		CHECKED BY M.SASAO		DATE '04/04/15		MOLEX INCORPORATED	
	30 OVER ±0.3		APPROVED BY M.SASAO		DATE '04/04/15		DOCUMENT NO. SD-53780-004	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 3 OF 3		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						